L Number	Hits	Search Text	DB	Time stamp
8	2207	((427/240) or (118/52) or (427/425) or (118/320)) CCLS	USPAT, US-PGPUB	2004/05/23 20 58
9	61	(((427/240) or (118/52) or (427/425) or (118/320)).CCLS.) and wafer and (hent\$3 same inert)	USPAT; US-PGPUB	2004/05/23 21:05
10	27	((((427/240) or (118/52) or (427/425) or (118/320)), CCLS,) and wafer and (heat\$3 same inert)) and @ad<19980320	USPAT, US-PGPUB	2004/05/23 20:59
11	8	(((((427/240) or (118/52) or (427/425) or (118/320)).CCLS.) and wafer and (heat\$3 same inert)) and @ad<19980320) and oxidiz\$3	USPAT, US-PGPUB	2004/05/23 20:55
12	921	semiconductor and Wafer and (heat\$3 same inert) and oxidiz\$3 and @adc19980320 not (((((4277240) or (118752) or (4277425) or (118730)) CCL\$) and wafer and (heat\$3 same inert)) and @adc19990320) and oxidiz\$3)	USPAT; US-PGPUB	2004/05/23 21:05
13	237	semiconductor and wafer and ((heat\$3 same inert) same oxidiz\$3) and @ad<19980320 not (((((427/240) or (118/52) or (427/425) or (118/52) or (18/52) and wafer and (heat\$3 same inert)) and @ad<19990320) and oxidiz\$3)	USPAT; US-PGPUB	2004/05/23 21:24
14	51	semiconductor and wafer ah and ((heat\$3 same inert) same oxidiz\$3) and @ad<19980320 not (((((427/240) or (118/52) or (427/425) or (118/320)) CCLS) and wafer and (heat\$3 same inert)) and @ad<19990320) and oxidiz\$3)	USPAT, US-PGPUB	2004/05/23 21:24
15	3	semiconductor and wafer.ab and ((heat\$3 same inert) same oxidiz\$3) ab. and @udc19980320 not (((((d277240) or (118/52) or (427/425) or (118/520)) CCLS:) and wafer and (heat\$3 same inert)) and @udc19990320) and oxidiz\$3)	USPAT; US-PGPUB	2004/05/23 21:06
16	16	(semiconductor and wafer ab. and ((heat\$3 same inert) same oxidiz\$3) and @ad<19980320 not (((((427/240) or (118/52) or (427/425) or (118/320)) CCLS.) and wafer sad (heat\$3 same inert)) and @ad<19990320) and oxidiz\$33) and (oxid\$3 same heat\$3)	USPAT; US-PGPUB	2004/05/23 21:07
17	29	semiconductor and wafer and ((heat53 same inert) same oxidiz53 same coat53) and @ad<19980320 not (((((4277240) or (118/52) or (427/425) or (118/520)) CCLS) and wafer and (heat53 same inert)) and @ad<19990320) and oxidiz53)	USPAT; US-PGPUB	2004/05/23 21 24
18	21	[semiconductor and wafer and (thexat3) same inerty same oxidia53 same: cont333 and @duck1999030 pot oft((cit/2740)) or (11892) or (127402) or (11892) or (127402) or (11892) or (127402) (CICS) and wafer and (hexat33 same inerty) and exidex1990020 pot exidex1990020 pot explores oxidia53) and @duck1990020 pot ((thexat35 same inert) same oxidix33) and @duck1990020 pot ((thexat35 same inert)) and exidex1990020 pot or (11892) or (274726) or (118925) or (274726) or (1189230) (CICS) and wafer and (hexat35 same inert)) and @duck19900320) and oxidix33)) and (cicst33 same inert).	USPAT; US-PGPUB	2004/05/23 21:42
20	276	(semiconductor adj wafer) and (((hot or heat or heating) adj plate) same pin)	USPAT, US-PGPUB	2004/05/23 21:44
21	99	(semiconductor adj wafer) and (((hot or heat or heating) adj plate) same pin) and inert	USPAT, US-PGPUB	2004/05/23 21:56
22	14	((semiconductor adj wafer) and (((hot or heat or heating) adj plate) same pin) and inert) and @ad<19980320	USPAT; US-PGPUB	2004/05/23 21:44
23	0	(wafer) and (((hot or heat or heating) adj plate) same pin) and inert and @ad<19980320 not (((semiconductor adj wafer) and (((hot or heat or heating) adj plate) same mn) and inert) and @ad<19980320)	USPAT; US-PGPUB	2004/05/23 21:56